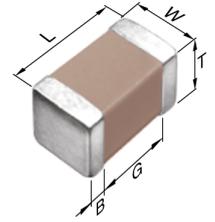


C2012JB1H474K125AB



TDK item description C2012JB1H474KT****

Applications	Commercial Grade
Feature	General General (Up to 50V)
Series	C2012 [EIA 0805]
Status	Production (Not Recommended for New Design)



Dimensions in mm

Size	
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	1.25mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)
	0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics	
Capacitance	470nF ±10%
Rated Voltage	50VDC
Temperature Characteristic	JB(±10%)
Dissipation Factor (Max.)	5%
Insulation Resistance (Min.)	1063MΩ

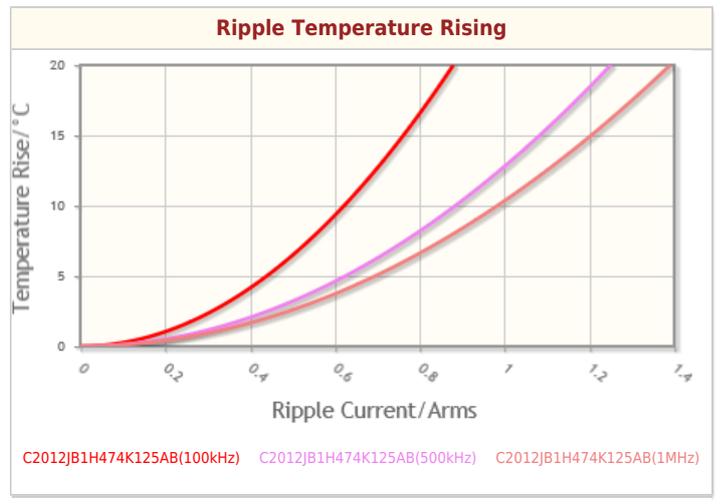
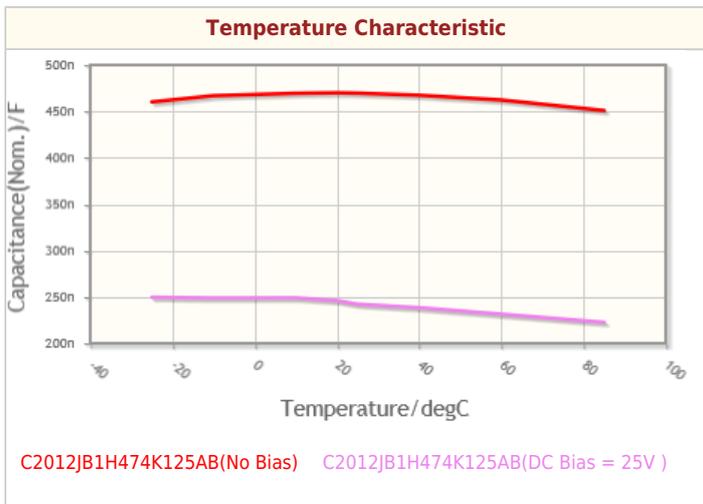
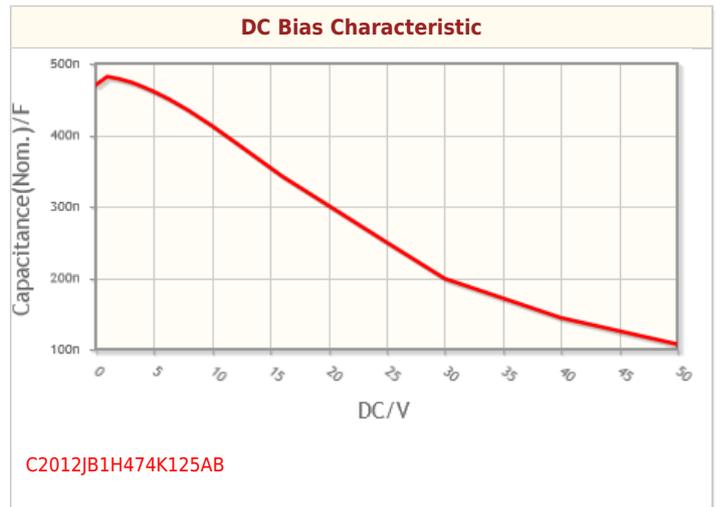
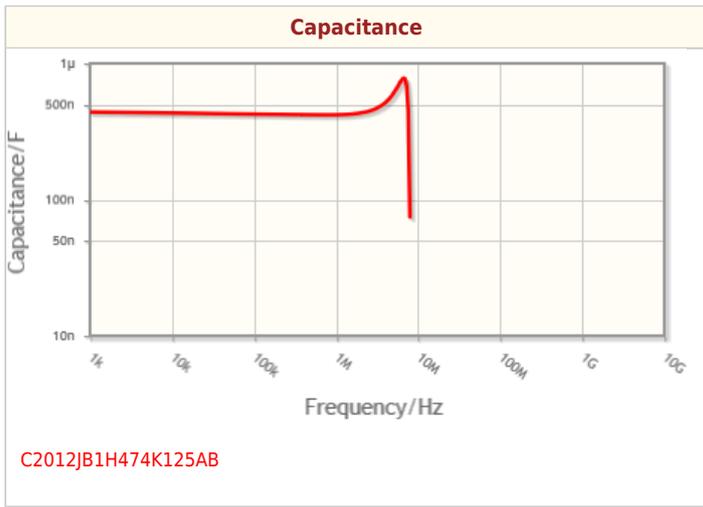
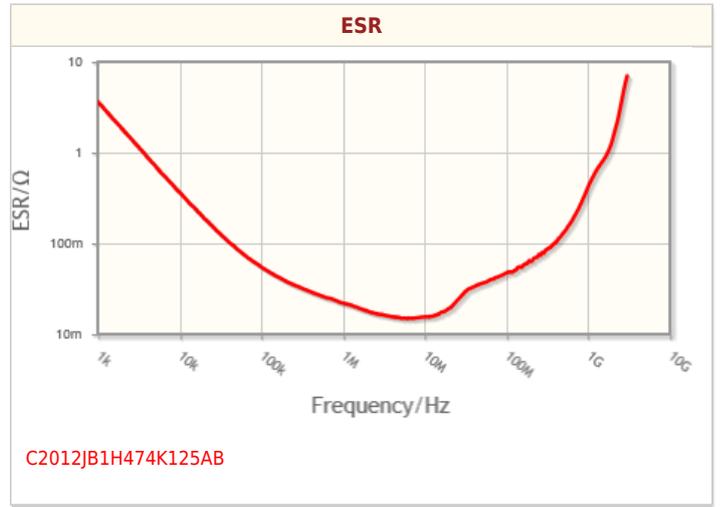
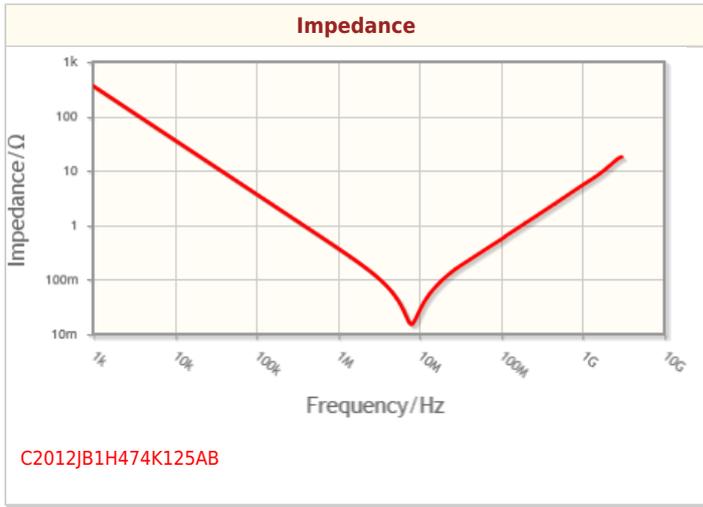
Other	
Soldering Method	Wave (Flow)
	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.

C2012JB1H474K125AB



Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

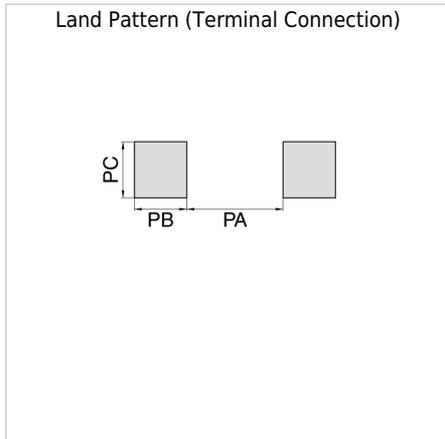


! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.

C2012JB1H474K125AB



Associated Images



! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.